

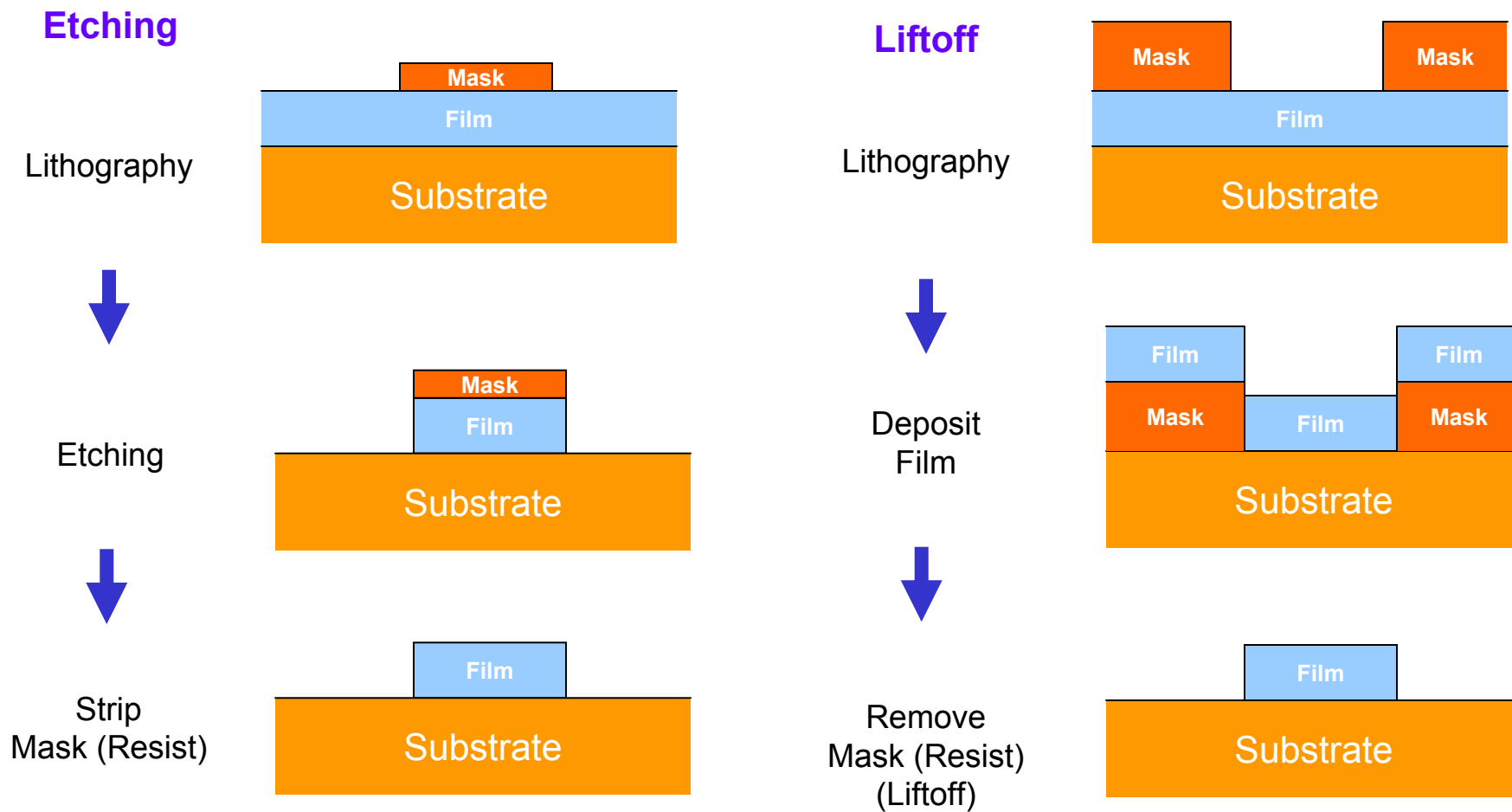
### III. Wet and Dry Etching

	Wet	Dry
Method	Chemical Solutions	Ion Bombardment or Chemical Reactive
Environment and Equipment	Atmosphere, Bath	Vacuum Chamber
Advantage	1) Low cost, easy to implement 2) High etching rate 3) Good selectivity for most materials	1) Capable of defining small feature size (< 100 nm)
Disadvantage	1) Inadequate for defining feature size < 1 $\mu$ m 2) Potential of chemical handling hazards 3) Wafer contamination issues	1) High cost, hard to implement 2) low throughput 3) Poor selectivity 4) Potential radiation damage
Directionality	Isotropic (Except for etching Crystalline Materials)	Anisotropic

NICHIA EXHIBIT 2010  
*Vizio, Inc. v. Nichia Corporation*  
Case IPR2018-00437



## Pattern Generation (Transfer): Etch vs. Liftoff



## Isotropic vs. Anisotropic Etching

Isotropic Etching: Etching rate is the same in both horizontal and vertical direction

Anisotropic Etching: Etching rate is different in horizontal and vertical direction

Lateral Etch Ratio:

$$R_L = \frac{\text{Horizontal Etch Rate } (r_H)}{\text{Vertical Etch Rate } (r_V)}$$

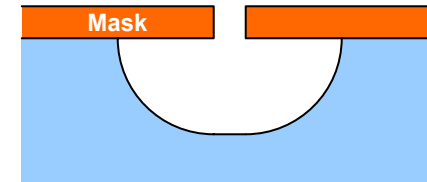
Isotropic Etching:  $R_L = 1$

Anisotropic Etching:  $0 < R_L < 1$

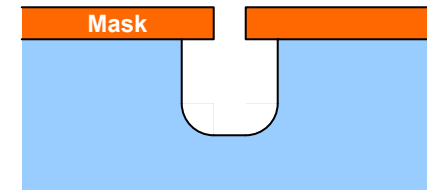
Directional Etching:  $R_L = 0$

**Bias:** the difference in lateral dimensions between the feature on mask and the actually etched pattern

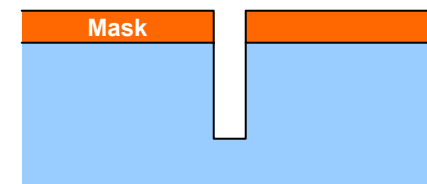
➔ smaller  $R_L$  results in smaller bias



$$R_L = 1$$



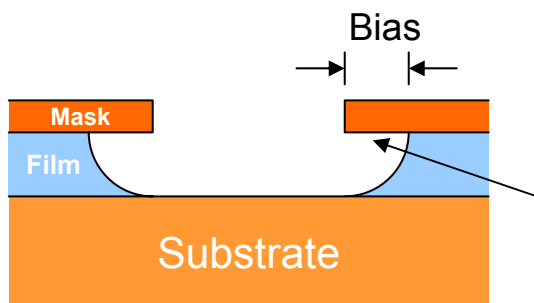
$$0 < R_L < 1$$



$$R_L = 0$$

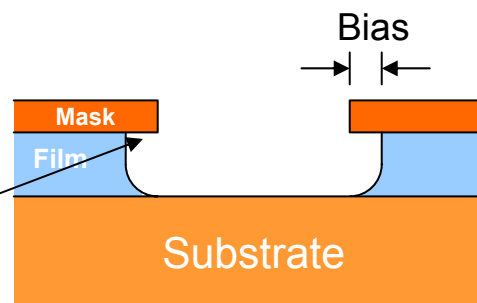


## “Under Cut” and “Over Etch”

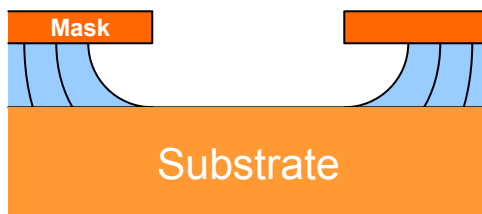


“Under Cut”  
Good for Lift-off

( $R_f = 1$ , pattern dimension  
is poorly defined)

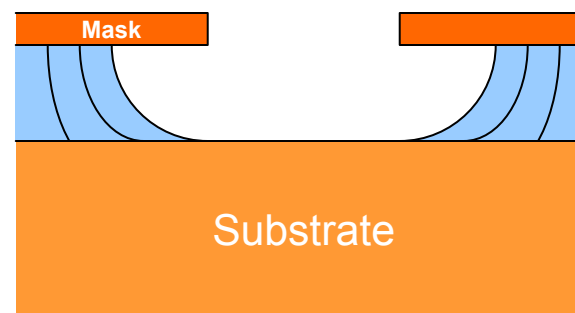


( $R_f = 0.5$ , pattern dimension  
is better defined)



Over-Etch

↪ results in more vertical profile  
but larger bias



Worse in thick film

↪ Poor CD control in  
thick film using wet etch



## Mask Erosion: Film-Mask Etching Selectivity

- 1) film horizontal etch rate ( $r_{fh}$ ) < mask horizontal etch rate ( $r_{mh}$ ):

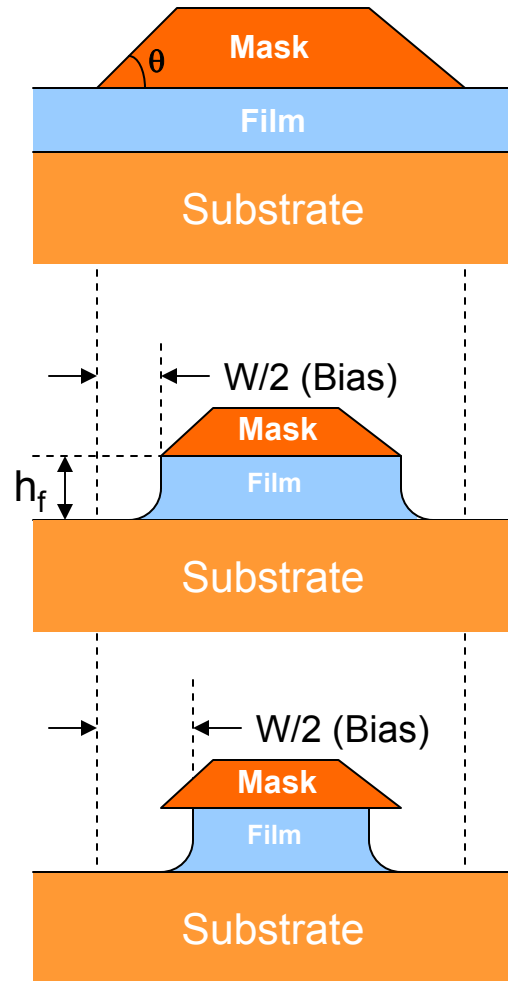
$$\frac{W}{h_f} (\%) = \frac{2}{S_{fm}} (\cot \theta + R_m)$$

$$R_{mL} = \frac{r_{mH}}{r_{mV}} \quad (\text{mask lateral etch ratio})$$

$$S_{fm} = \frac{r_{fV}}{r_{mV}} \quad (\text{ratio of film and mask vertical etching rate} \\ \text{– selectivity})$$

- 2) If film horizontal etch rate ( $r_{fh}$ ) > mask horizontal etch rate ( $r_{mh}$ ):

$$\frac{W}{h_f} (\%) = 2R_m$$



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